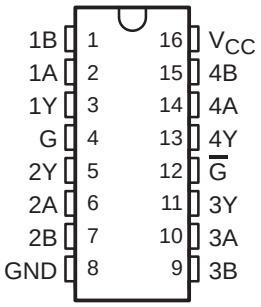
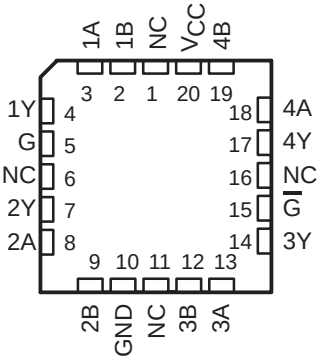
- **Meet or Exceed the Requirements of TIA/EIA-422-B, TIA/EIA-423-B, and TIA/EIA-485-A and ITU Recommendations V.10, V.11, X.26, and X.27**
- **Designed for Multipoint Bus Transmission on Long Bus Lines in Noisy Environments**
- **3-State Outputs**
- **Common-Mode Input Voltage Range of –12 V to 12 V**
- **Input Sensitivity . . . ±200 mV**
- **Input Hysteresis . . . 50 mV Typ**
- **High Input Impedance . . . 12 kΩ Min**
- **Operate From Single 5-V Supply**
- **Low Power Requirements**
- **Pin-to-Pin Replacement for AM26LS32**

SN55173 . . . J PACKAGE
SN65173, SN75173 . . . D OR N PACKAGE
(TOP VIEW)



SN55173 . . . FK PACKAGE
(TOP VIEW)



NC – No internal connection

THE SN55173 IS NOT RECOMMENDED FOR NEW DESIGNS.

description

The SN55173, SN65173, and SN75173 are monolithic quadruple differential line receivers with 3-state outputs. They are designed to meet the requirements of TIA/EIA-422-B, TIA/EIA-423-B, TIA/EIA-485-A, and several ITU recommendations. The standards are for balanced multipoint bus transmission at rates up to 10 megabits per second. The four receivers share two OR enable inputs, one active when high, the other active when low. These devices feature high input impedance, input hysteresis for increased noise immunity, and input sensitivity of ±200 mV over a common-mode input voltage range of –12 V to 12 V. Fail-safe design specifies that if the inputs are open circuited, the outputs are always high. The SN65173 and SN75173 are designed for optimum performance when used with the SN75172 or SN75174 quad differential line drivers.

The SN55173 is characterized over the full military temperature range of –55°C to 125°C. The SN65173 is characterized for operation from –40°C to 85°C. The SN75173 is characterized for operation from 0°C to 70°C.

AVAILABLE OPTIONS

T_A	PACKAGED DEVICES			
	PLASTIC SMALL OUTLINE (D)	PLASTIC CHIP CARRIER (FK)	CERAMIC DIP (J)	PLASTIC DIP (N)
0°C to 70°C	SN75173D	—	—	SN75173N
–40°C to 85°C	SN65173D	—	—	SN65173N
–55°C to 125°C	—	SN55173FK	SN55173J	—

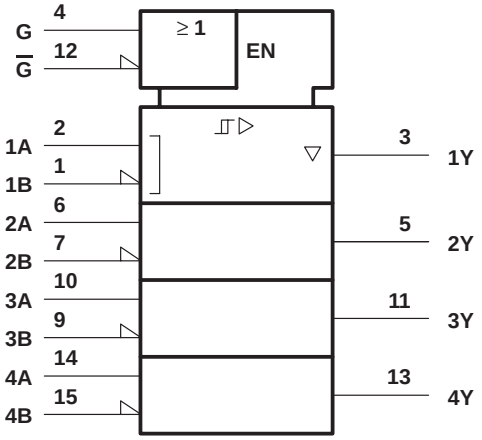
The D package is available taped and reeled. Add the suffix R to the device type (e.g., SN75173DR).

FUNCTION TABLE
(each receiver)

DIFFERENTIAL A–B	ENABLES		OUTPUT Y
	G	$\overline{G}$	
$V_{ID} \geq 0.2$ V	H	X	H
	X	L	H
–0.2 V < V_{ID} < 0.2 V	H	X	?
	X	L	?
$V_{ID} \leq$ –0.2 V	H	X	L
	X	L	L
X	L	H	Z
Open circuit	X	L	H
	H	X	H

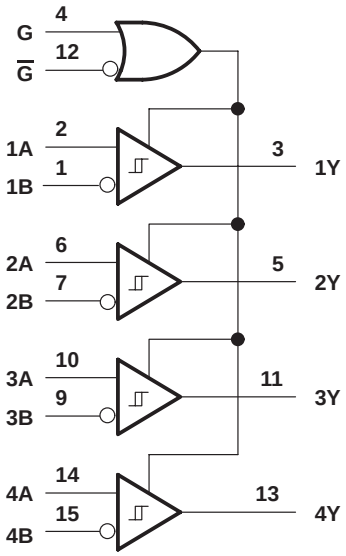
H = high level, L = low level, ? = indeterminate,
X = irrelevant, Z = high impedance (off)

logic symbol †



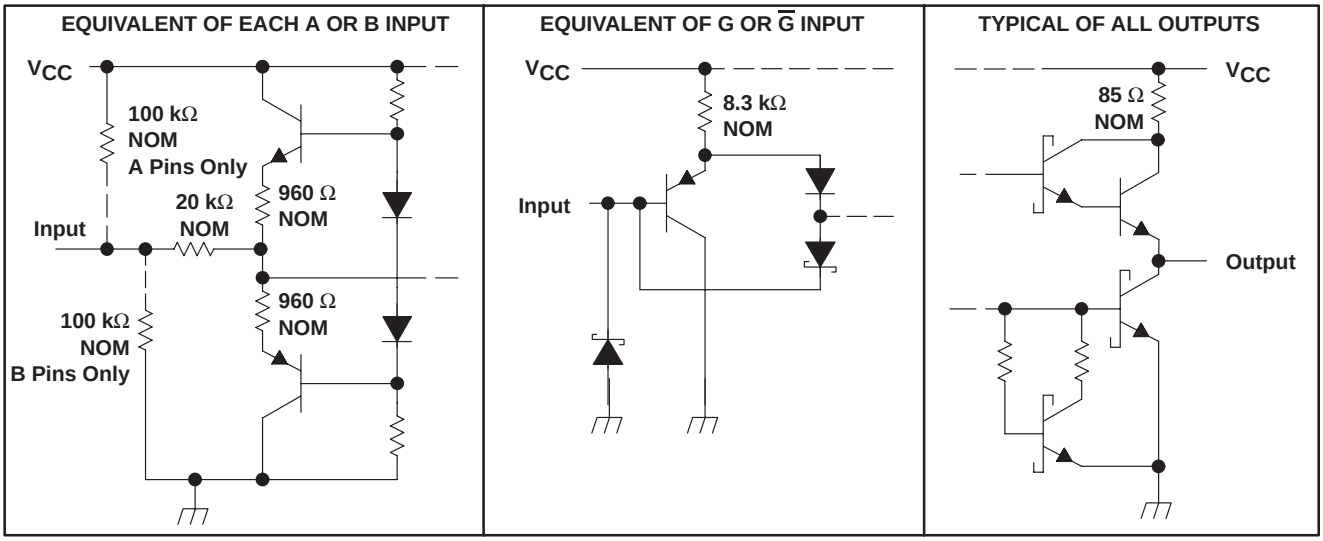
† This symbol is in accordance with ANSI/IEEE Std 91-1984 and IEC Publication 617-12.
Pin numbers shown are for the D, J, and N packages.

logic diagram (positive logic)



Pin numbers shown are for the D, J, and N packages.

schematics of inputs and outputs



absolute maximum ratings over operating free-air temperature range (unless otherwise noted)†

Supply voltage, V_{CC} (see Note 1) . . . . . 7 V
Input voltage (V_I or B inputs) . . . . . ±25 V
Differential input voltage, V_{ID} (see Note 2) . . . . . ±25 V
Enable input voltage, V_I . . . . . 7 V
Low-level output current, I_{OL} . . . . . 50 mA
Package thermal impedance, θ_{JA} (see Note 3): D package . . . . . 73°C/W
N package . . . . . 67°C/W
Continuous total dissipation . . . . . See Dissipation Rating Table
Case temperature for 60 seconds, T_C: FK package . . . . . 260°C
Lead temperature 1,6 mm (1/16 inch) from case for 10 seconds: D or N package . . . . . 260°C
Lead temperature 1,6 mm (1/16 inch) from case for 60 seconds: J package . . . . . 300°C
Storage temperature range, T_{stg} . . . . . –65°C to 150°C

† Stresses beyond those listed under “absolute maximum ratings” may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under “recommended operating conditions” is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.

NOTES: 1. All voltage values, except differential input voltage, are with respect to network ground terminal.
2. Differential input voltage is measured at the noninverting input with respect to the corresponding inverting input.
3. The package thermal impedance is calculated in accordance with JESD 51.

DISSIPATION RATING TABLE

PACKAGE	$T_A \le 25°C$ POWER RATING	DERATING FACTOR	$T_A = 70°C$ POWER RATING	$T_A = 125°C$ POWER RATING
FK	1375 mW	11 mW/°C	880 mW	275 mW
J	1375 mW	11 mW/°C	880 mW	275 mW

recommended operating conditions

		MIN	NOM	MAX	UNIT
Supply voltage, V_{CC}	SN55173	4.5	5	5.5	V
	SN65173, SN75173	4.75	5	5.25	V
Common-mode input voltage, V_{IC}				±12	V
Differential input voltage, V_{ID}				±12	V
High-level enable-input voltage, V_{IH}		2			V
Low-level enable-input voltage, V_{IL}				0.8	V
High-level output current, I_{OH}				–400	μA
Low-level output current, I_{OL}				16	mA
Operating free-air temperature, T_A	SN55173	–55		125	°C
	SN65173	–40		85	
	SN75173	0		70	

electrical characteristics over recommended ranges of common-mode input voltage, supply voltage, and operating free-air temperature

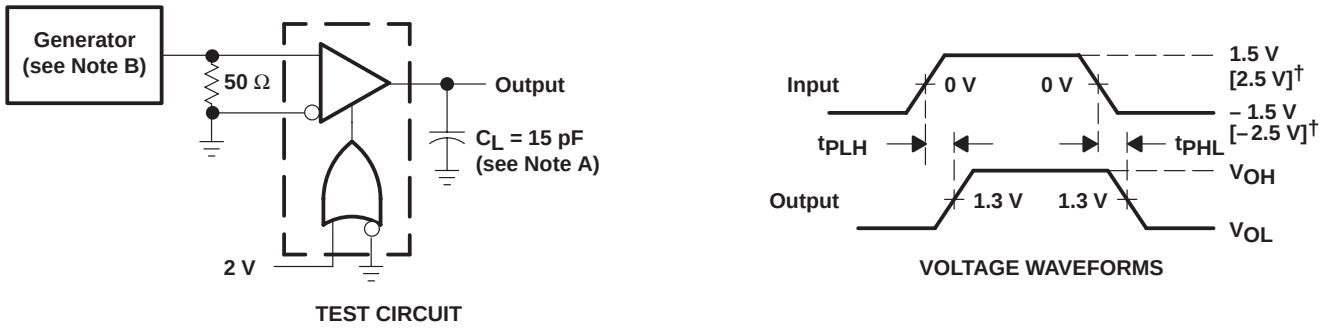
PARAMETER		TEST CONDITIONS			MIN	TYP†	MAX	UNIT
V_{IT+}	Positive-going input threshold voltage	V_O = 2.7 V,	I_O = –0.4 mA				0.2	V
$V_{IT–}$	Negative-going input threshold voltage	V_O = 0.5 V,	I_O = 16 mA		–0.2‡			V
V_{hys}	Hysteresis ($V_{IT+} – V_{IT–}$)	See Figure 4				50		mV
V_{IK}	Enable-input clamp voltage	I_I = –18 mA					–1.5	V
V_{OH}	High-level output voltage	V_{ID} = 200 mV,	I_{OH} = –400 μA	SN55173	2.5			V
				SN65173, SN75173	2.7			V
V_{OL}	Low-level output voltage	V_{ID} = –200 mV,	See Figure 1	I_{OL} = 8 mA			0.45	V
				I_{OL} = 16 mA			0.5	
I_{OZ}	High-impedance-state output current	V_O = 0.4 V to 2.4 V					±20	μA
I_I	Line input current	Other input at 0 V,	See Note 3	V_I = 12 V			1	mA
				V_I = –7 V			–0.8	
I_{IH}	High-level enable-input current	V_{IH} = 2.7 V					20	μA
I_{IL}	Low-level enable-input current	V_{IL} = 0.4 V					–100	μA
r_i	Input resistance				12			kΩ
I_{OS}	Short-circuit output current				–15		–85	mA
I_{CC}	Supply current	Outputs disabled					70	mA

† All typical values are at V_{CC} = 5 V, T_A = 25°C.
‡ The algebraic convention, in which the less positive (more negative) limit is designated as minimum, is used in this data sheet for threshold voltage levels only.
NOTE 3: Refer to TIA/EIA-422-B and TIA/EIA-423-B for exact conditions.

switching characteristics, V_{CC} = 5 V, T_A = 25°C

PARAMETER		TEST CONDITIONS		MIN	TYP	MAX	UNIT
t_{PLH}	Propagation delay time, low-to-high-level output	V_{ID} = –1.5 V to 1.5 V, C_L = 15 pF,	See Figure 1		20	35	ns
t_{PHL}	Propagation delay time, high-to-low-level output				22	35	ns
t_{PZH}	Output enable time to high level	C_L = 15 pF,	See Figure 2		17	22	ns
t_{PZL}	Output enable time to low level	C_L = 15 pF,	See Figure 3		20	25	ns
t_{PHZ}	Output disable time from high level	C_L = 5 pF,	See Figure 2		21	30	ns
t_{PLZ}	Output disable time from low level	C_L = 5 pF,	See Figure 3		30	40	ns

PARAMETER MEASUREMENT INFORMATION

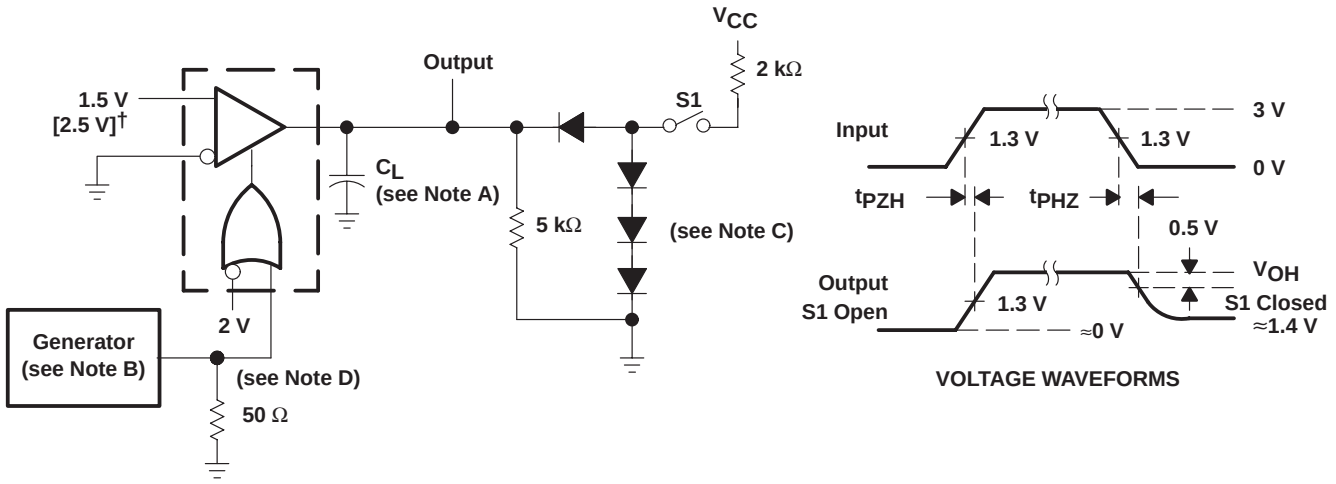


† Voltage for the SN55173 only.

NOTES: A. C_L includes probe and jig capacitance.

B. The input pulse is supplied by a generator having the following characteristics: PRR = 1 MHz, duty cycle = 50%, $t_r \le 6$ ns, $t_f \le 6$ ns, $Z_O = 50\ \Omega$.

Figure 1. t_{PLH}, t_{PHL} Test Circuit and Voltage Waveforms



† Voltage for the SN55173 only.

NOTES: A. C_L includes probe and jig capacitance.

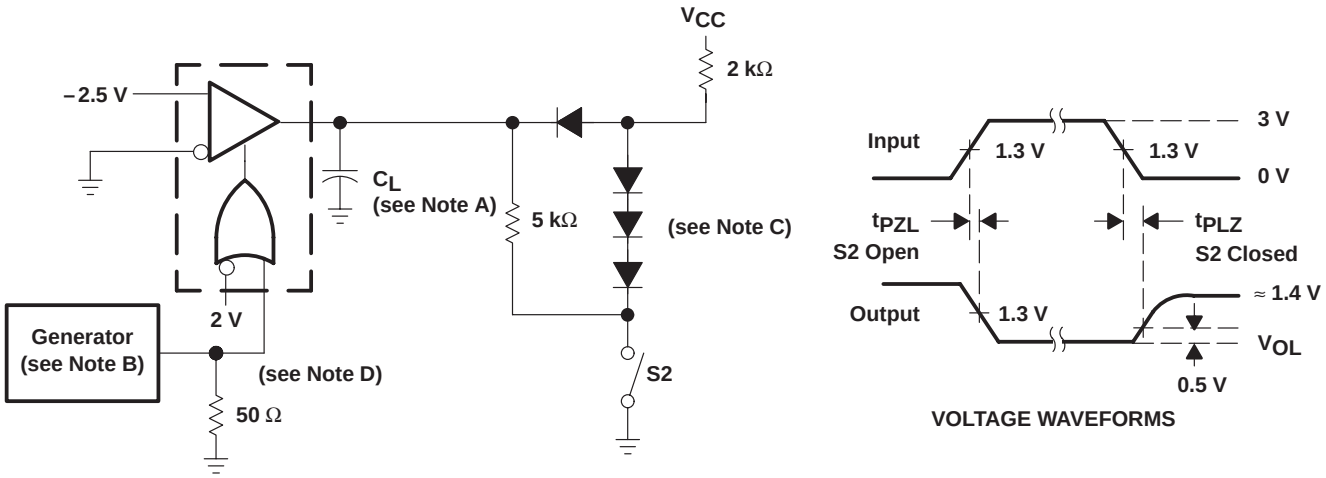
B. The input pulse is supplied by a generator having the following characteristics: PRR = 1 MHz, duty cycle = 50%, $t_r \le 6$ ns, $t_f \le 6$ ns, $Z_O = 50\ \Omega$.

C. All diodes are 1N916, or equivalent.

D. To test the active-low enable $\overline{G}$, ground G and apply an inverted input waveform to $\overline{G}$.

Figure 2. t_{PHZ}, t_{PZH} Test Circuit and Voltage Waveforms

PARAMETER MEASUREMENT INFORMATION



NOTES: A. C_L includes probe and jig capacitance.
B. The input pulse is supplied by a generator having the following characteristics: PRR = 1 MHz, duty cycle = 50%, $t_r \le 6$ ns, $t_f \le 6$ ns, $Z_O = 50\ \Omega$.
C. All diodes are 1N916, or equivalent.
D. To test the active-low enable $\overline{G}$, ground G and apply an inverted input waveform to $\overline{G}$.

Figure 3. t_{PZL}, t_{PLZ} Test Circuit and Voltage Waveforms

TYPICAL CHARACTERISTICS†

OUTPUT VOLTAGE vs DIFFERENTIAL INPUT VOLTAGE

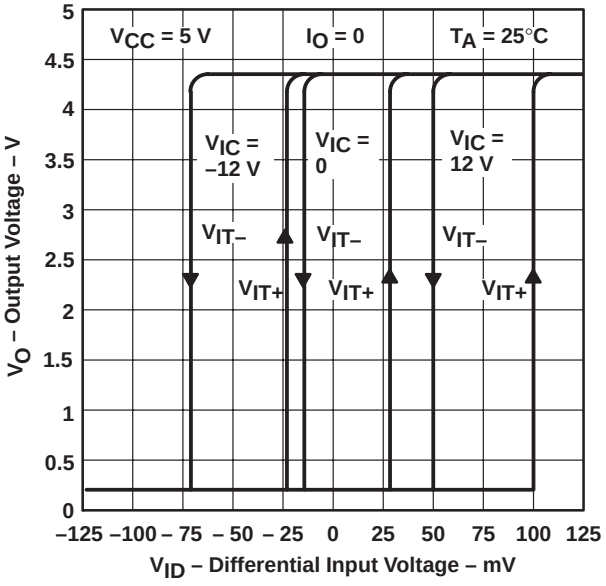


Figure 4

HIGH-LEVEL OUTPUT VOLTAGE vs HIGH-LEVEL OUTPUT CURRENT

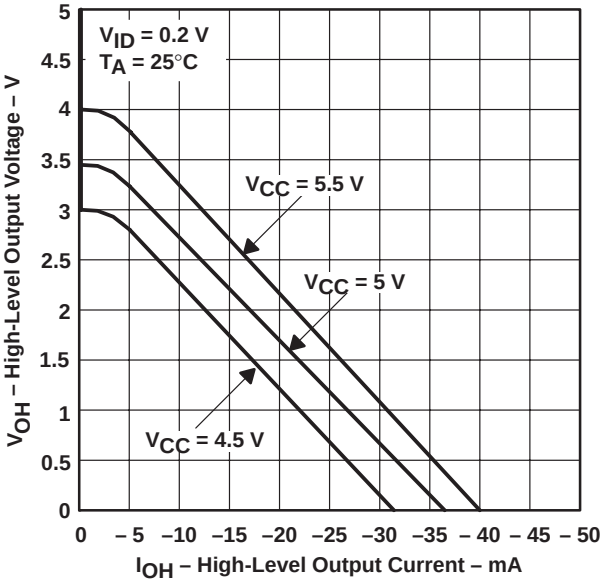


Figure 5

† Operation of the device at these or any other conditions beyond those indicated under “recommended operating conditions” is not implied.

TYPICAL CHARACTERISTICS†

HIGH-LEVEL OUTPUT VOLTAGE vs FREE-AIR TEMPERATURE

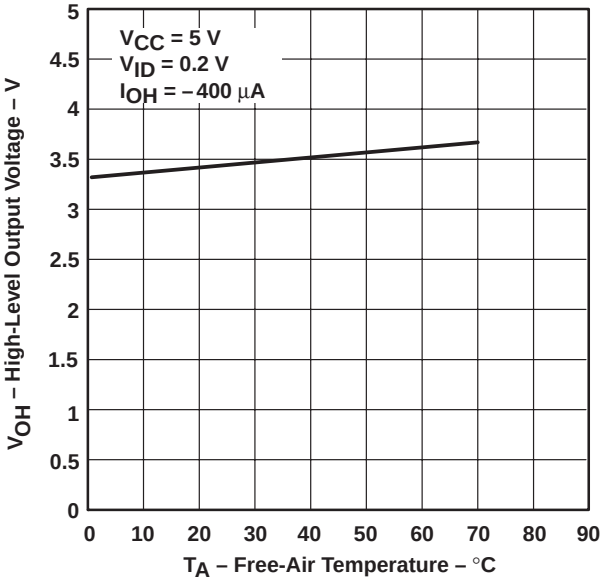


Figure 6

LOW-LEVEL OUTPUT VOLTAGE vs LOW-LEVEL OUTPUT CURRENT

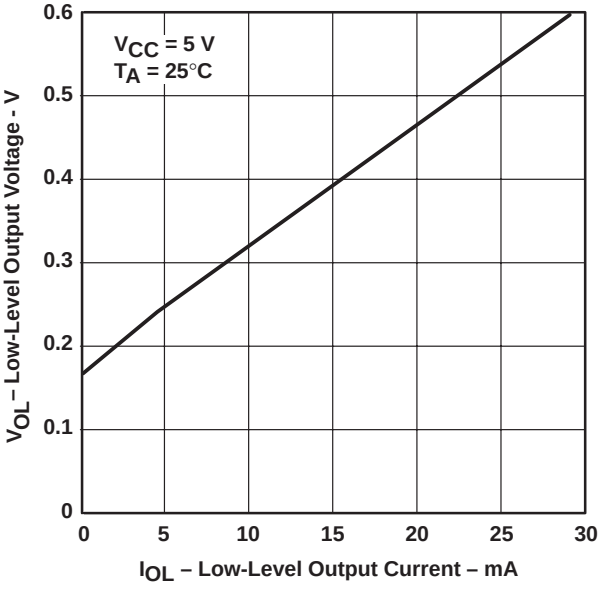


Figure 7

LOW-LEVEL OUTPUT VOLTAGE vs FREE-AIR TEMPERATURE

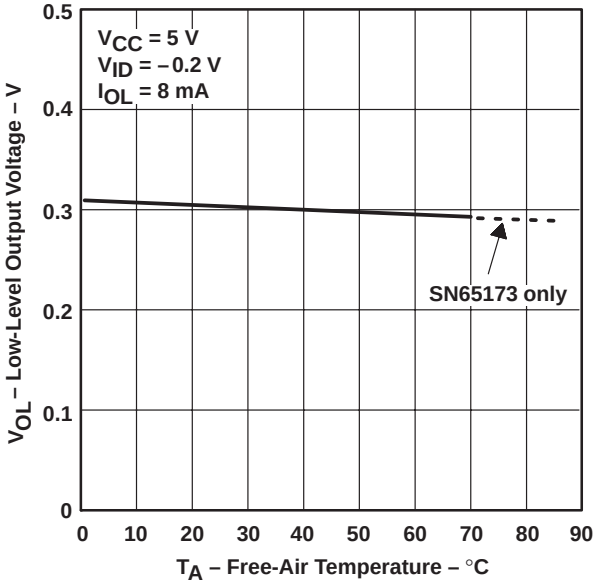


Figure 8

OUTPUT VOLTAGE vs ENABLE G VOLTAGE

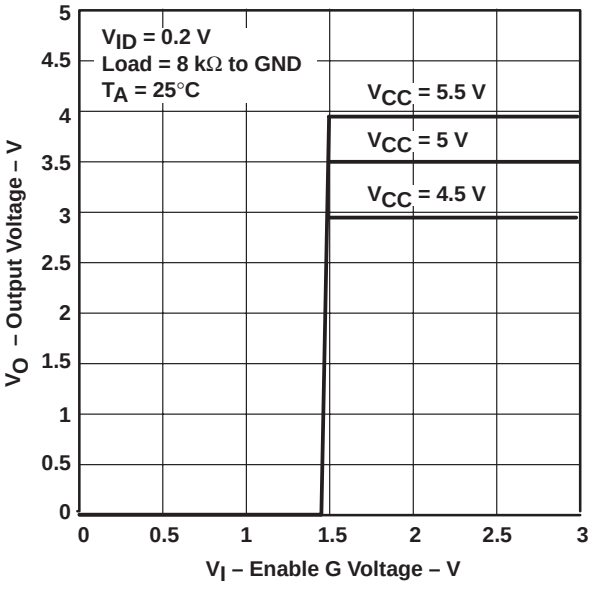


Figure 9

† Operation of the device at these or any other conditions beyond those indicated under “recommended operating conditions” is not implied.

TYPICAL CHARACTERISTICS

OUTPUT VOLTAGE vs ENABLE G VOLTAGE

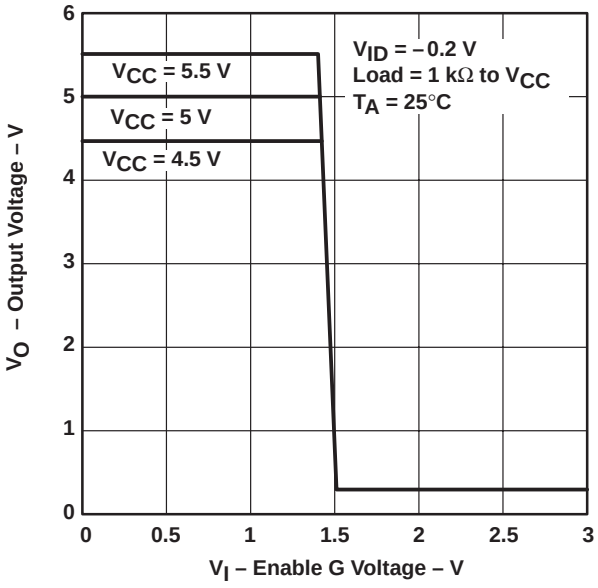


Figure 10

INPUT CURRENT vs INPUT VOLTAGE

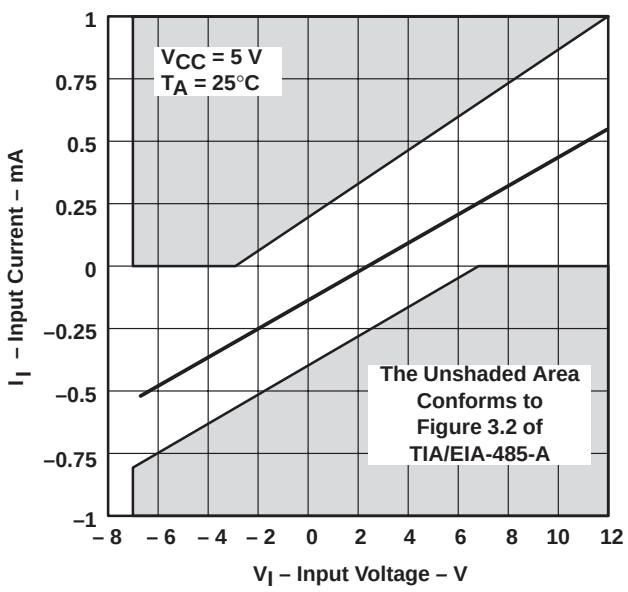
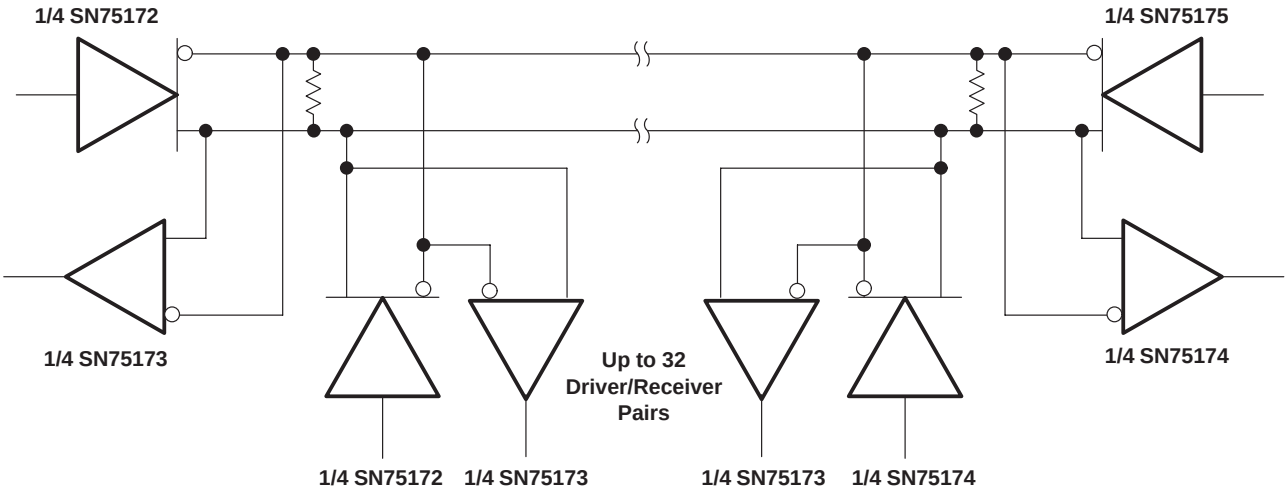


Figure 11

APPLICATION INFORMATION



NOTE A: The line should be terminated at both ends in its characteristic impedance. Stub lengths off the main line should be kept as short as possible.

Figure 12. Typical Application Circuit

PACKAGING INFORMATION

Orderable Device	Status (1)	Package Type	Package Drawing	Pins	Package Qty	Eco Plan (2)	Lead/Ball Finish (6)	MSL Peak Temp (3)	Op Temp (°C)	Device Marking (4/5)	Samples
SN55173J	ACTIVE	CDIP	J	16	1	TBD	A42	N / A for Pkg Type	-55 to 125	SN55173J	Samples
SN75173D	ACTIVE	SOIC	D	16	40	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	0 to 70	SN75173	Samples
SN75173DE4	ACTIVE	SOIC	D	16	40	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	0 to 70	SN75173	Samples
SN75173DG4	ACTIVE	SOIC	D	16	40	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	0 to 70	SN75173	Samples
SN75173DR	ACTIVE	SOIC	D	16	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	0 to 70	SN75173	Samples
SN75173DRG4	ACTIVE	SOIC	D	16	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	0 to 70	SN75173	Samples
SN75173N	ACTIVE	PDIP	N	16	25	Pb-Free (RoHS)	CU NIPDAU	N / A for Pkg Type	0 to 70	SN75173N	Samples
SN75173NE4	ACTIVE	PDIP	N	16	25	Pb-Free (RoHS)	CU NIPDAU	N / A for Pkg Type	0 to 70	SN75173N	Samples
SN75173NSR	ACTIVE	SO	NS	16	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	0 to 70	SN75173	Samples
SNJ55173J	ACTIVE	CDIP	J	16	1	TBD	A42	N / A for Pkg Type	-55 to 125	SNJ55173J	Samples

(1) The marketing status values are defined as follows:
ACTIVE: Product device recommended for new designs.
LIFEBUY: TI has announced that the device will be discontinued, and a lifetime-buy period is in effect.
NRND: Not recommended for new designs. Device is in production to support existing customers, but TI does not recommend using this part in a new design.
PREVIEW: Device has been announced but is not in production. Samples may or may not be available.
OBSOLETE: TI has discontinued the production of the device.

(2) Eco Plan - The planned eco-friendly classification: Pb-Free (RoHS), Pb-Free (RoHS Exempt), or Green (RoHS & no Sb/Br) - please check http://www.ti.com/productcontent for the latest availability information and additional product content details.
TBD: The Pb-Free/Green conversion plan has not been defined.
Pb-Free (RoHS): TI's terms "Lead-Free" or "Pb-Free" mean semiconductor products that are compatible with the current RoHS requirements for all 6 substances, including the requirement that lead not exceed 0.1% by weight in homogeneous materials. Where designed to be soldered at high temperatures, TI Pb-Free products are suitable for use in specified lead-free processes.
Pb-Free (RoHS Exempt): This component has a RoHS exemption for either 1) lead-based flip-chip solder bumps used between the die and package, or 2) lead-based die adhesive used between the die and leadframe. The component is otherwise considered Pb-Free (RoHS compatible) as defined above.
Green (RoHS & no Sb/Br): TI defines "Green" to mean Pb-Free (RoHS compatible), and free of Bromine (Br) and Antimony (Sb) based flame retardants (Br or Sb do not exceed 0.1% by weight in homogeneous material)

(3) MSL, Peak Temp. - The Moisture Sensitivity Level rating according to the JEDEC industry standard classifications, and peak solder temperature.

(4) There may be additional marking, which relates to the logo, the lot trace code information, or the environmental category on the device.

(5) Multiple Device Markings will be inside parentheses. Only one Device Marking contained in parentheses and separated by a "~" will appear on a device. If a line is indented then it is a continuation of the previous line and the two combined represent the entire Device Marking for that device.

(6) Lead/Ball Finish - Orderable Devices may have multiple material finish options. Finish options are separated by a vertical ruled line. Lead/Ball Finish values may wrap to two lines if the finish value exceeds the maximum column width.

OTHER QUALIFIED VERSIONS OF SN55173, SN75173 :

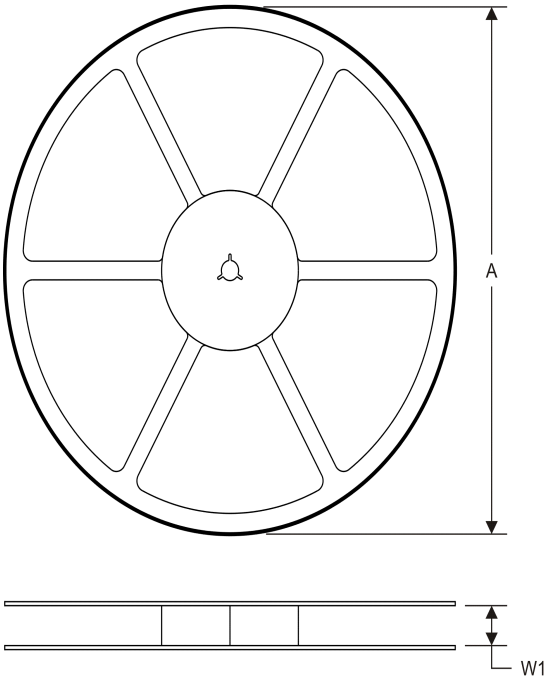
- Catalog: SN75173
- Military: SN55173

NOTE: Qualified Version Definitions:

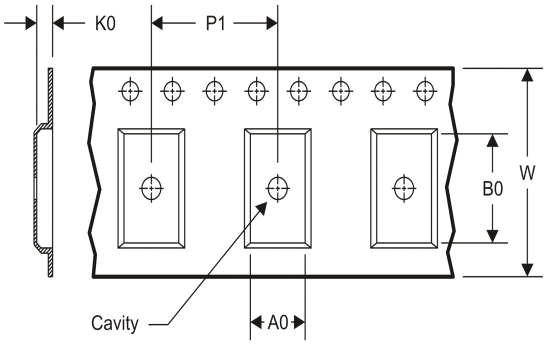
- Catalog - TI's standard catalog product
- Military - QML certified for Military and Defense Applications

TAPE AND REEL INFORMATION

REEL DIMENSIONS



TAPE DIMENSIONS



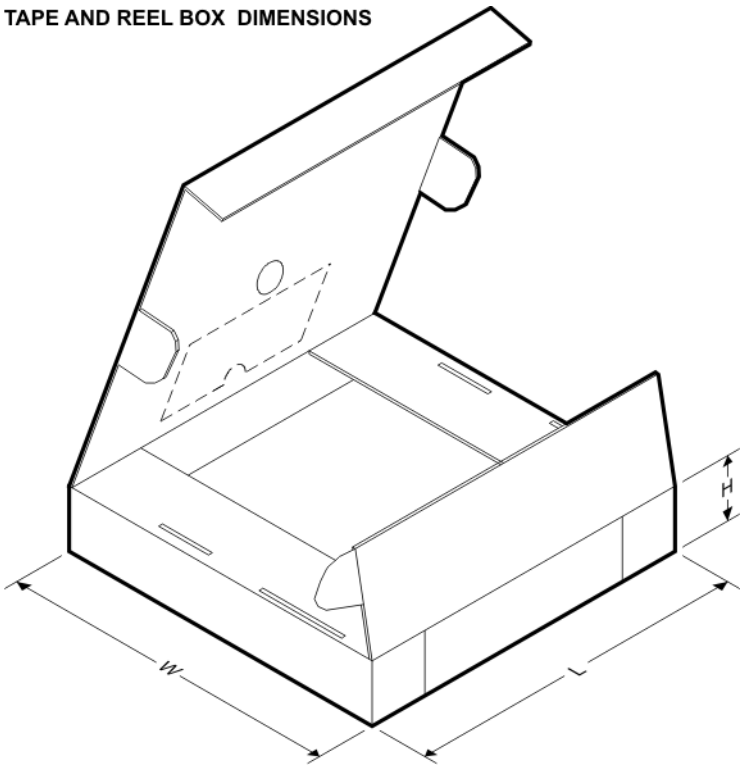
A0	Dimension designed to accommodate the component width
B0	Dimension designed to accommodate the component length
K0	Dimension designed to accommodate the component thickness
W	Overall width of the carrier tape
P1	Pitch between successive cavity centers

TAPE AND REEL INFORMATION

*All dimensions are nominal

Device	Package Type	Package Drawing	Pins	SPQ	Reel Diameter (mm)	Reel Width W1 (mm)	A0 (mm)	B0 (mm)	K0 (mm)	P1 (mm)	W (mm)	Pin1 Quadrant
SN75173DR	SOIC	D	16	2500	330.0	16.4	6.5	10.3	2.1	8.0	16.0	Q1
SN75173NSR	SO	NS	16	2000	330.0	16.4	8.2	10.5	2.5	12.0	16.0	Q1

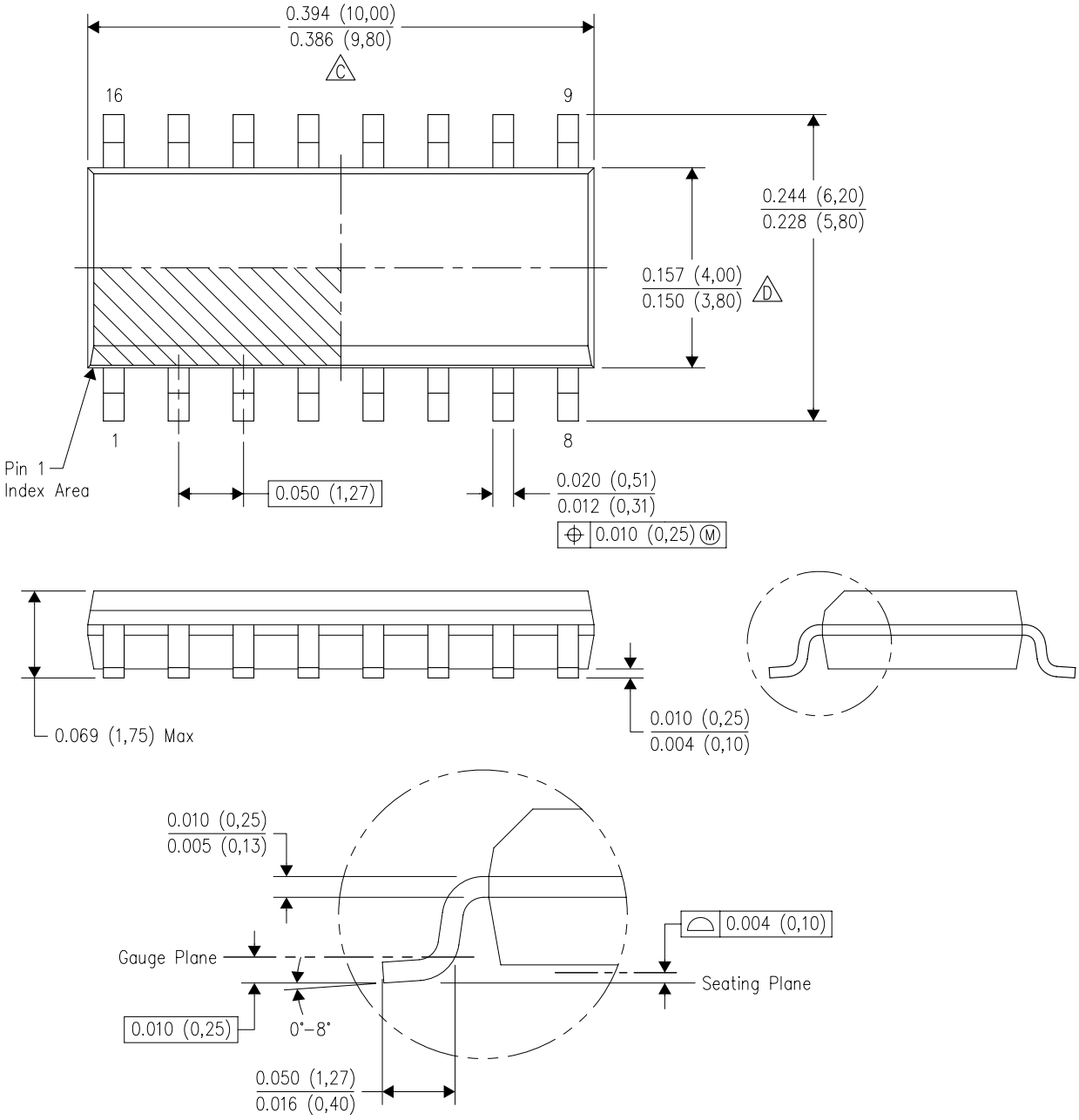
TAPE AND REEL BOX DIMENSIONS



*All dimensions are nominal

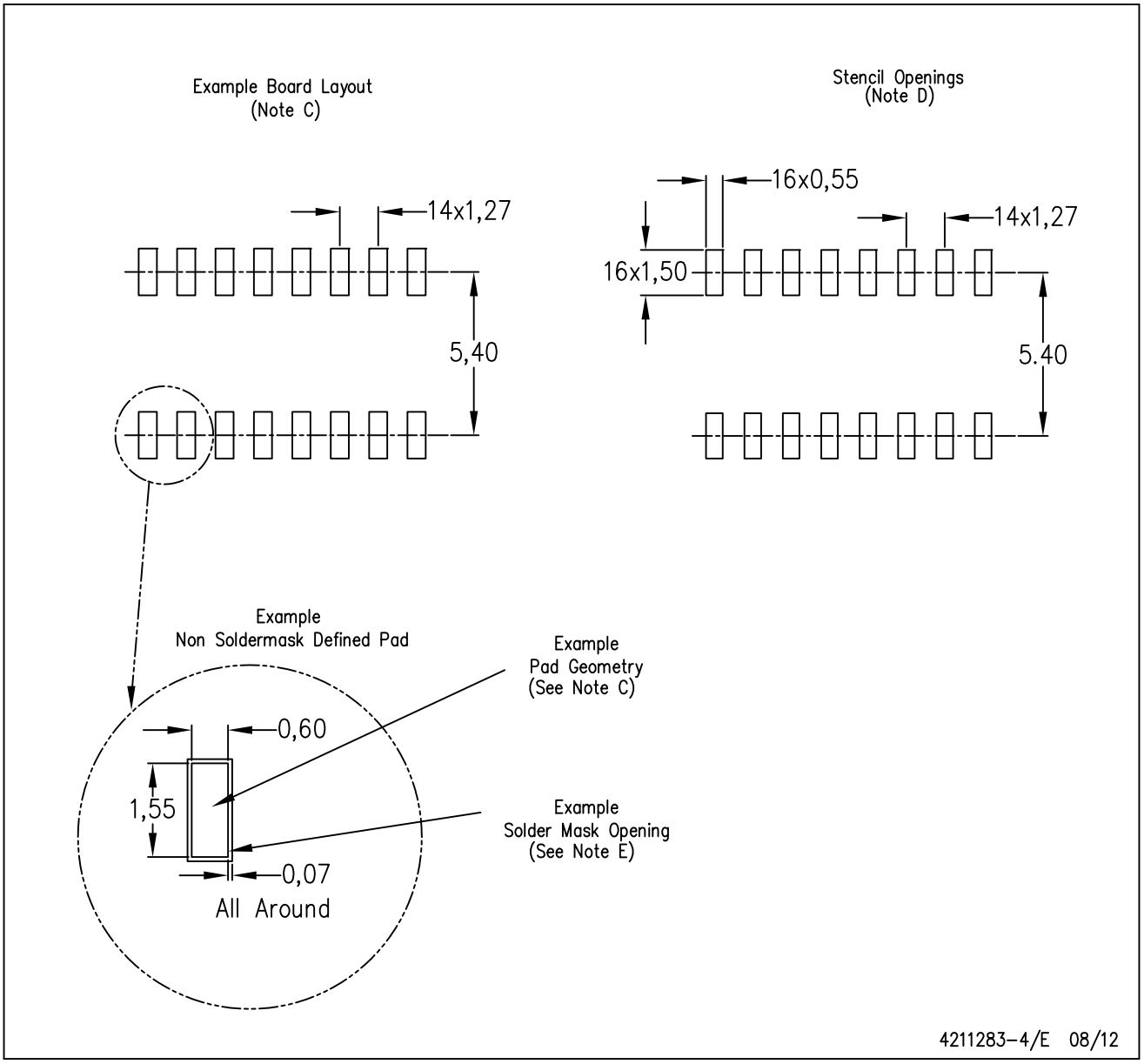
Device	Package Type	Package Drawing	Pins	SPQ	Length (mm)	Width (mm)	Height (mm)
SN75173DR	SOIC	D	16	2500	333.2	345.9	28.6
SN75173NSR	SO	NS	16	2000	367.0	367.0	38.0

D (R–PDSO–G16) PLASTIC SMALL OUTLINE



NOTES:
A. All linear dimensions are in inches (millimeters).
B. This drawing is subject to change without notice.
C. Body length does not include mold flash, protrusions, or gate burrs. Mold flash, protrusions, or gate burrs shall not exceed 0.006 (0,15) each side.
D. Body width does not include interlead flash. Interlead flash shall not exceed 0.017 (0,43) each side.
E. Reference JEDEC MS–012 variation AC.

D (R–PDSO–G16) PLASTIC SMALL OUTLINE

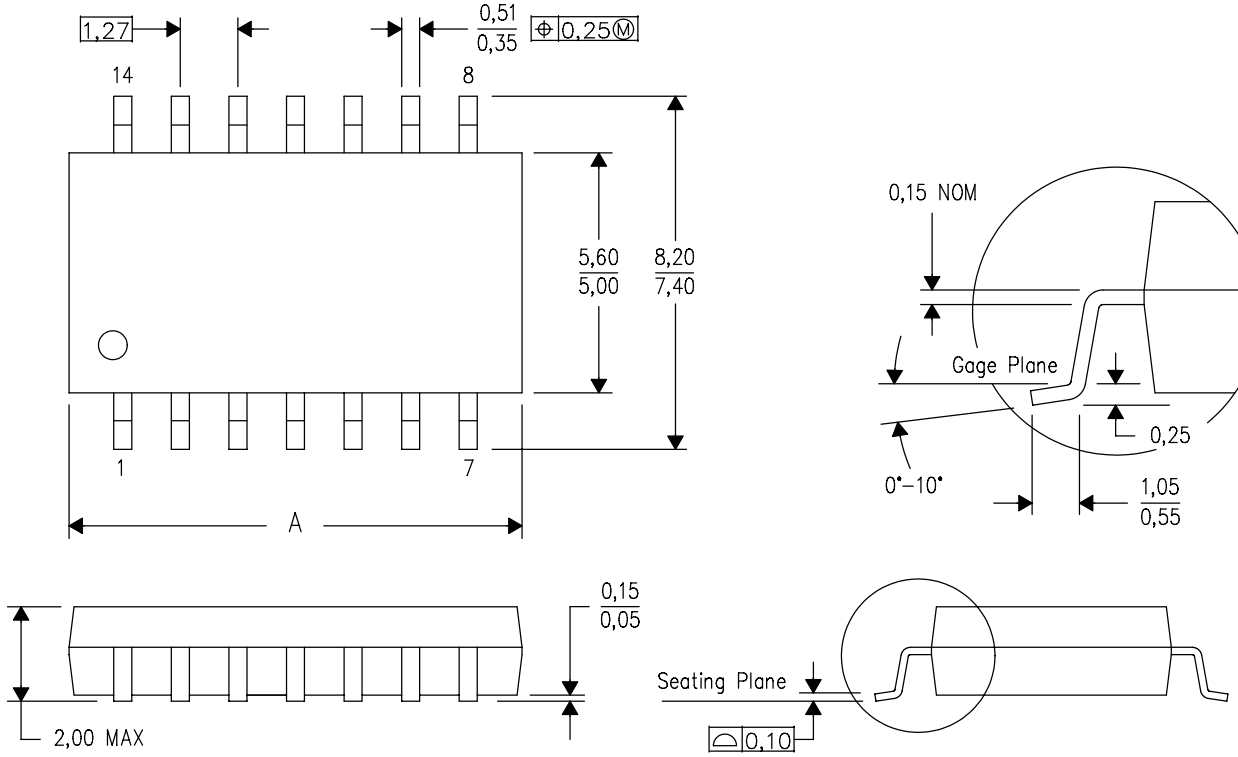


NOTES:
A. All linear dimensions are in millimeters.
B. This drawing is subject to change without notice.
C. Publication IPC–7351 is recommended for alternate designs.
D. Laser cutting apertures with trapezoidal walls and also rounding corners will offer better paste release. Customers should contact their board assembly site for stencil design recommendations. Refer to IPC–7525 for other stencil recommendations.
E. Customers should contact their board fabrication site for solder mask tolerances between and around signal pads.

MECHANICAL DATA

NS (R-PDSO-G)** **PLASTIC SMALL-OUTLINE PACKAGE**

14-PINS SHOWN



DIM \ PINS **	14	16	20	24
A MAX	10,50	10,50	12,90	15,30
A MIN	9,90	9,90	12,30	14,70

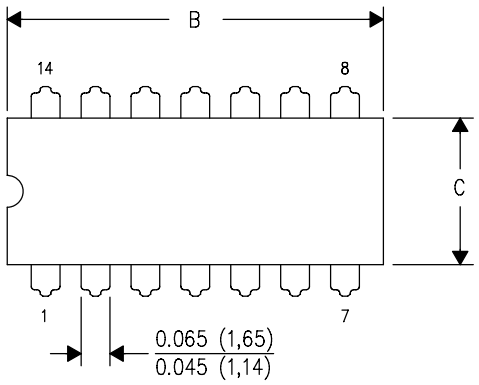
4040062/C 03/03

NOTES:
A. All linear dimensions are in millimeters.
B. This drawing is subject to change without notice.
C. Body dimensions do not include mold flash or protrusion, not to exceed 0,15.

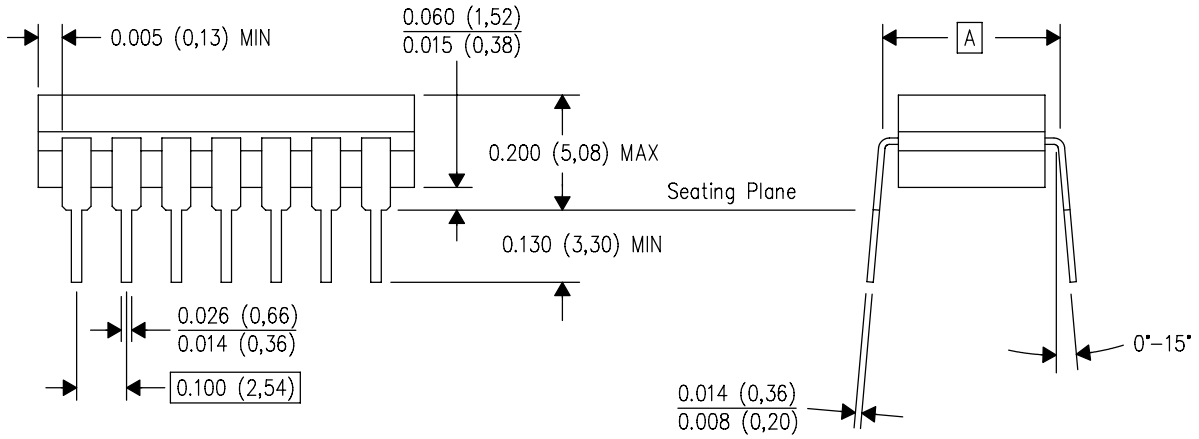
J (R–GDIP–T**)

14 LEADS SHOWN

CERAMIC DUAL IN–LINE PACKAGE



DIM \ PINS **	14	16	18	20
A	0.300 (7,62) BSC	0.300 (7,62) BSC	0.300 (7,62) BSC	0.300 (7,62) BSC
B MAX	0.785 (19,94)	.840 (21,34)	0.960 (24,38)	1.060 (26,92)
B MIN	—	—	—	—
C MAX	0.300 (7,62)	0.300 (7,62)	0.310 (7,87)	0.300 (7,62)
C MIN	0.245 (6,22)	0.245 (6,22)	0.220 (5,59)	0.245 (6,22)



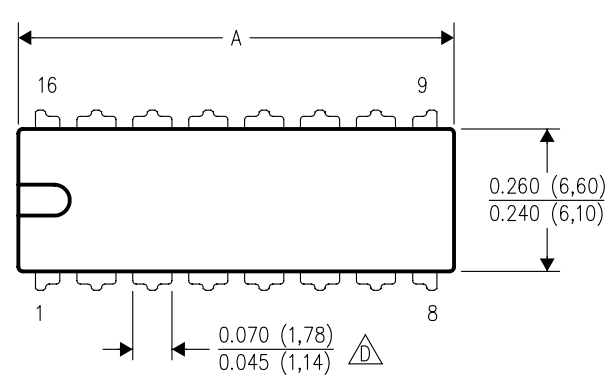
4040083/F 03/03

NOTES:
A. All linear dimensions are in inches (millimeters).
B. This drawing is subject to change without notice.
C. This package is hermetically sealed with a ceramic lid using glass frit.
D. Index point is provided on cap for terminal identification only on press ceramic glass frit seal only.
E. Falls within MIL STD 1835 GDIP1–T14, GDIP1–T16, GDIP1–T18 and GDIP1–T20.

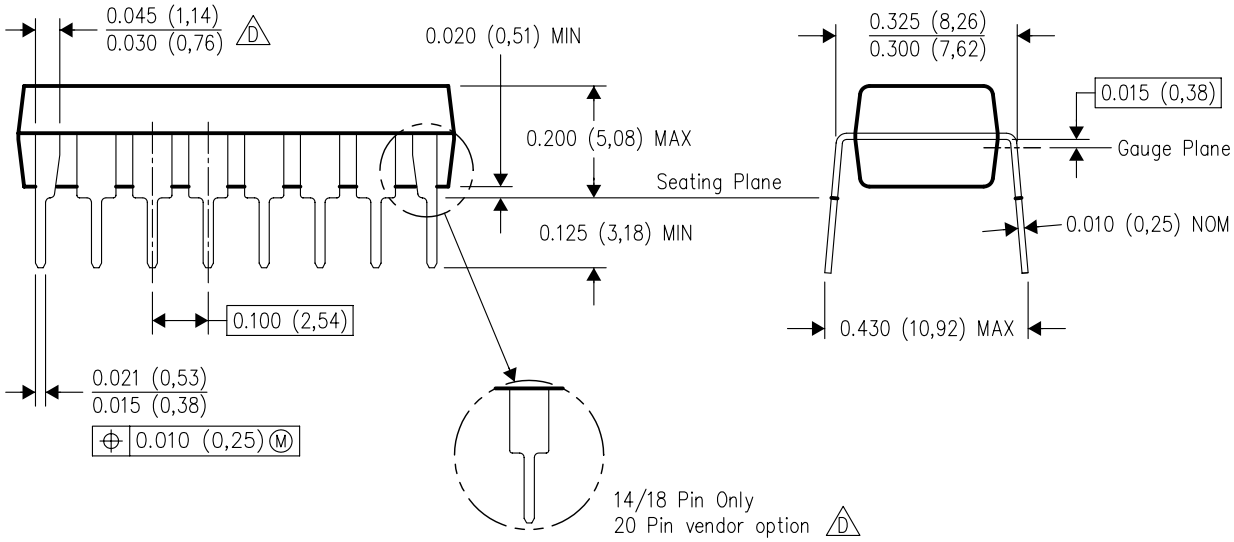
N (R–PDIP–T**)

PLASTIC DUAL–IN–LINE PACKAGE

16 PINS SHOWN



DIM \ PINS **	14	16	18	20
A MAX	0.775 (19,69)	0.775 (19,69)	0.920 (23,37)	1.060 (26,92)
A MIN	0.745 (18,92)	0.745 (18,92)	0.850 (21,59)	0.940 (23,88)
MS–001 VARIATION (C)	AA	BB	AC	AD



4040049/E 12/2002

NOTES:
A. All linear dimensions are in inches (millimeters).
B. This drawing is subject to change without notice.
C. Falls within JEDEC MS–001, except 18 and 20 pin minimum body length (Dim A).
D. The 20 pin end lead shoulder width is a vendor option, either half or full width.

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